



Electromagnetic Nondestructive Testing and Evaluation

Guest Editor:

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Message from the Guest Editor

Electromagnetic nondestructive testing is playing a significant part in nondestructive testing around the world. The developing usage of electromagnetic nondestructive testing has put forward new requirements and challenges for promoting research in related fields. Therefore, this Special Issue aims to introduce new ideas and experimental results from the principle, characterization and mechanism of electromagnetic nondestructive testing to sensors, signal processing and intelligent evaluation in practical applications.

This Special Issue will publish high-quality original research papers in the following fields:

- Principle and mechanism of electromagnetic nondestructive testing method;
- Electromagnetic characterization of electromagnetic excitation and damage or tension;
- Magneto-electric coupling and sensing mechanism and technology;
- Electromagnetic nondestructive testing electrical signal processing;
- Electromagnetic nondestructive testing digital signal processing and intelligent evaluation;
- Electromagnetic nondestructive testing sensors, equipment and applications.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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